

degree of accuracy by semiconductor processing, it is possible to eliminate errors in assembling, unlike the case where semiconductor pixels are discretely arranged on a circumference.

Claims

1. A polygon-type semiconductor detector for use in a high-speed X-ray CT, said detector comprising:

a plurality of detector modules each of which is formed by arranging a plurality of X-ray detection pixels unidirectionally on a single planar semiconductor substrate,

wherein said polygon-type semiconductor detector for use in a high-speed X-ray CT is formed by polygonally arranging the plurality of said detector modules around a measuring area.



2. A polygon-type semiconductor detector for use in a high-speed X-ray CT according to claim 1, wherein a CdTe semiconductor is used as said semiconductor substrate.

3. A polygon-type semiconductor detector for use in a high-speed X-ray CT according to claim 1, wherein said single semiconductor substrate is provided on a printed circuit board, and wherein the plurality of X-ray detection